

# A Discussion on Utilization of Heat Pipe and Vapor Chamber Technology as a Primary Device for Heat Extraction from Photon Absorber

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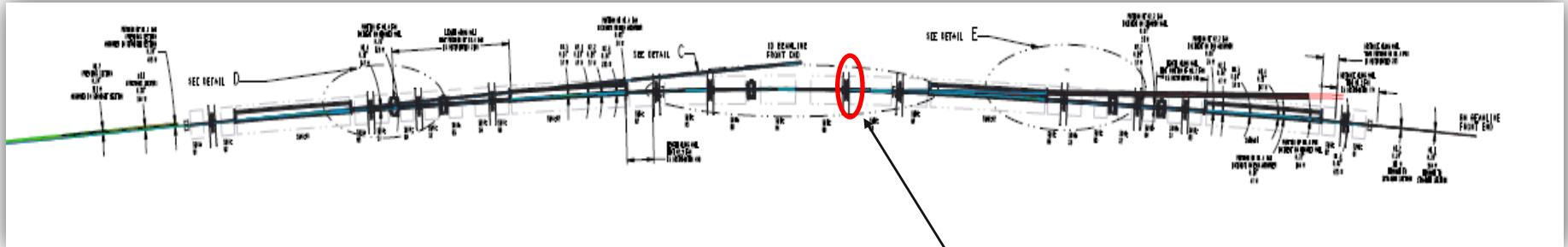


# Outline

- Problem Description
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- Heat Pipe
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  - Theoretical Limitations of Heat Transport
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  - Conductivity From Thermal Resistance
- FEA (cont.)
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- Conclusions

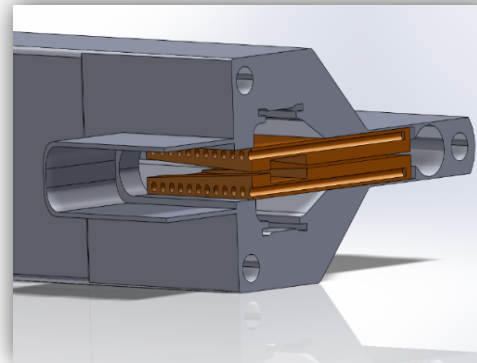


# Problem Description

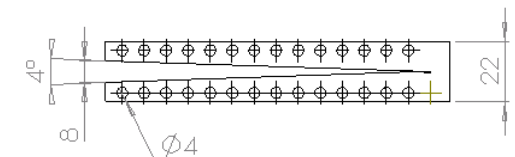
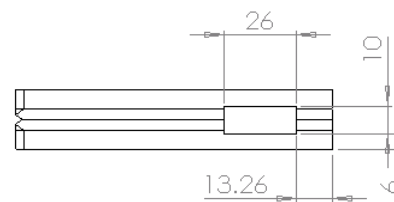
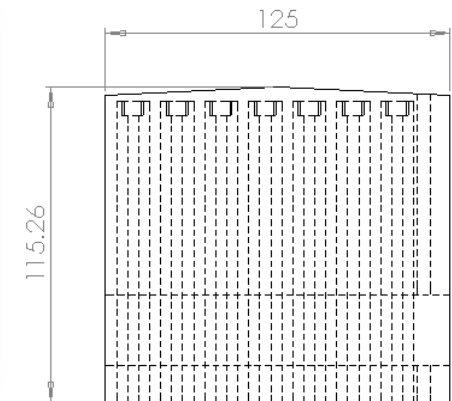


FEA Thermal Steady State Analysis [1]

- Current Design of B:CA1
  - 2.9KW
  - Limited space
- Problems
  - Max. Temperature
  - Temperature Gradient and Thermal Stresses



B:CA1 Absorber in Assembly [1]

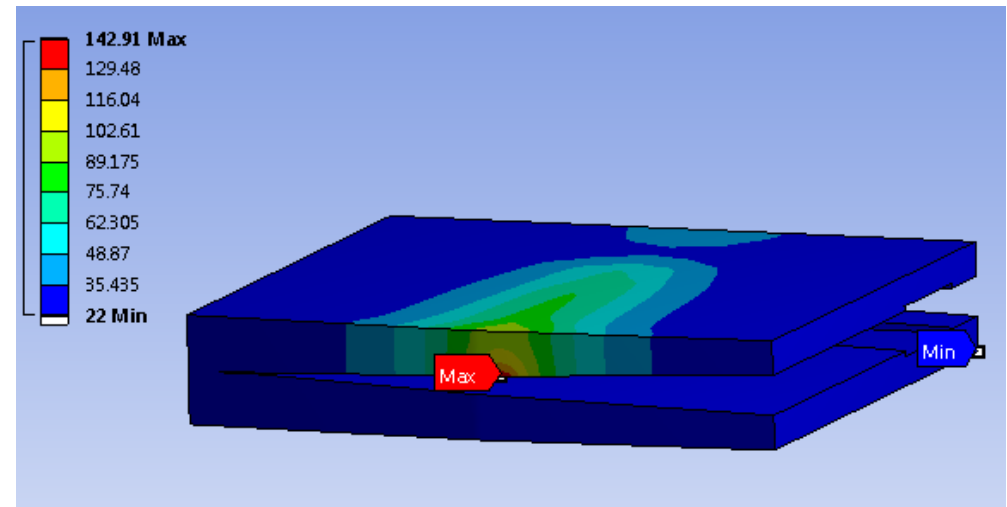


B:CA1 Drawing [1]

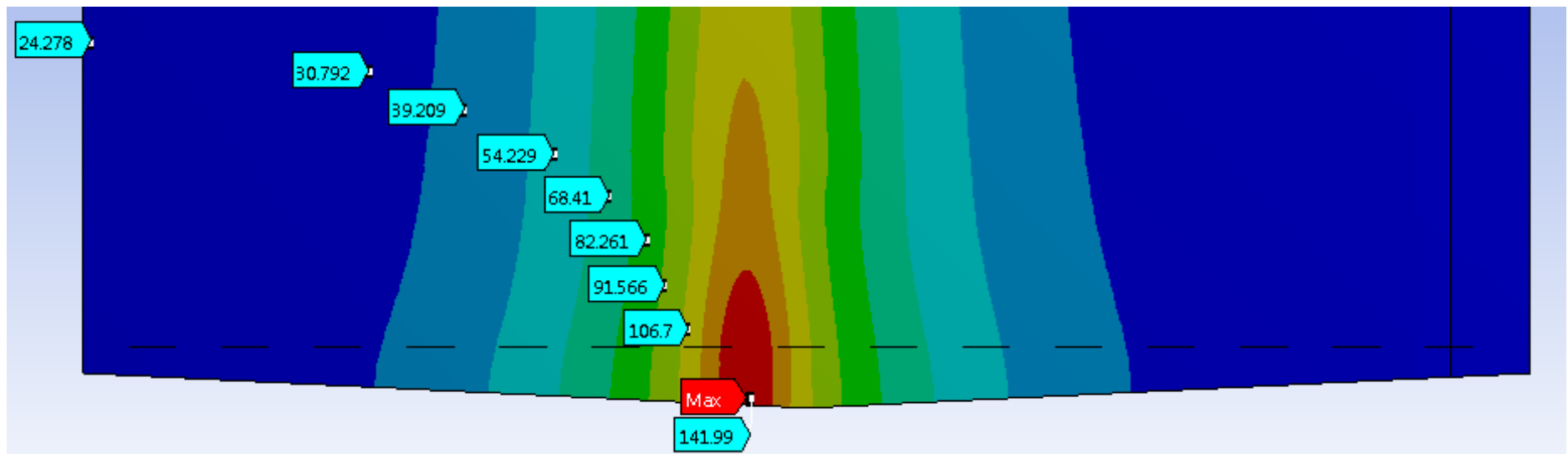
# FEA Result of Baseline Design

## ■ Thermal Analysis of B:CA1

- Worst Case Scenario
- Risk Imposing Thermal Gradient
- High Maximum Temperature



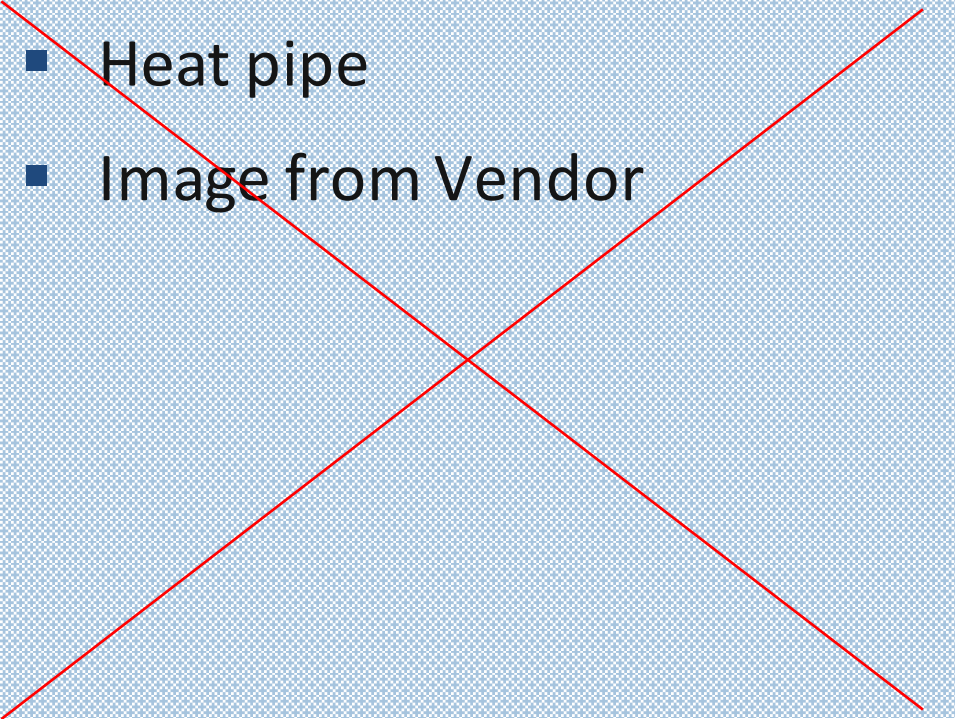
*Water Cooled Thermal Steady State FEA*



# The Heat pipe



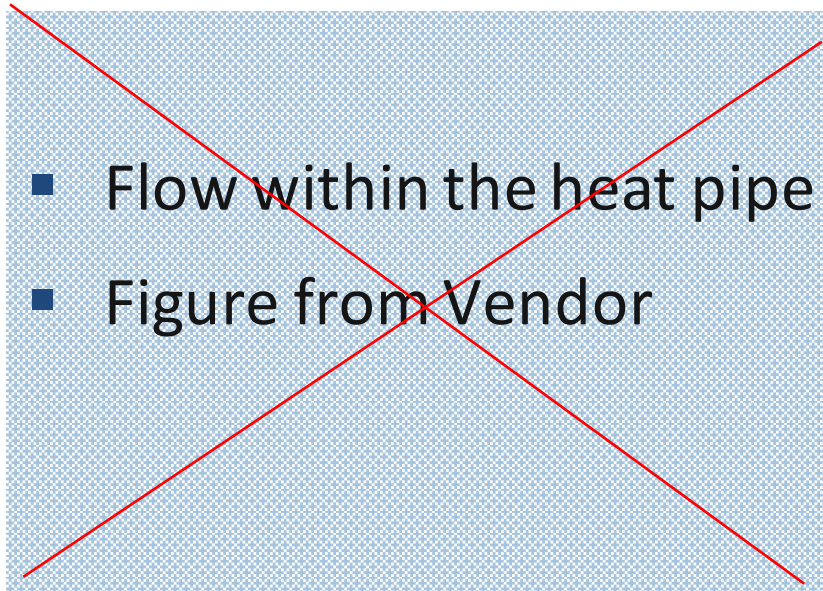
# What is the Heat pipe?

- 
- Heat pipe
  - Image from Vendor

Ref: [http://www.thermoguide.co.il/Heat\\_pipes.html](http://www.thermoguide.co.il/Heat_pipes.html)

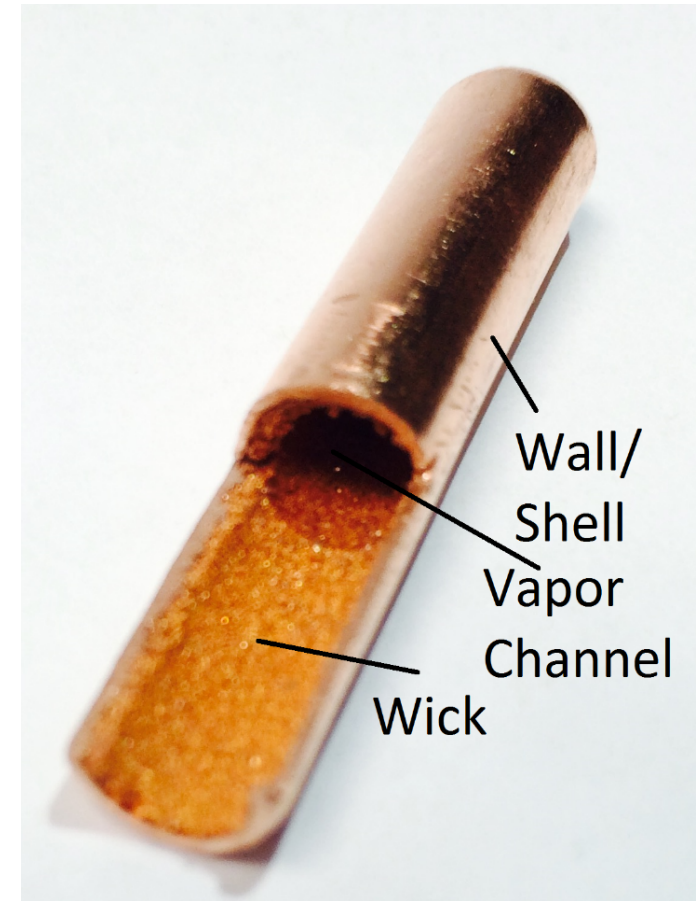


# Heat Pipe Background



*Heat Pipe Flow Diagram[2]*

- Two Phase Heat Transport Device
  - Phase Change Phenomenon w/ Anti-Parallel Flow
  - Large Variety of Wick Types
  - Flexible Geometry
  - Low Vibration Expectations
  - **Equivalent** Thermal Conductivity that is 10 to 1000 times higher than metal in same shape



*Copper-Water Sintered Powder Heat Pipe (Cut Open)*

$$h_c = 5000 - 200,000 \text{ W/m}^2/\text{K}$$
$$k = 2000 - 100,000 \text{ W/m/K}$$

# Advantage and Limitations





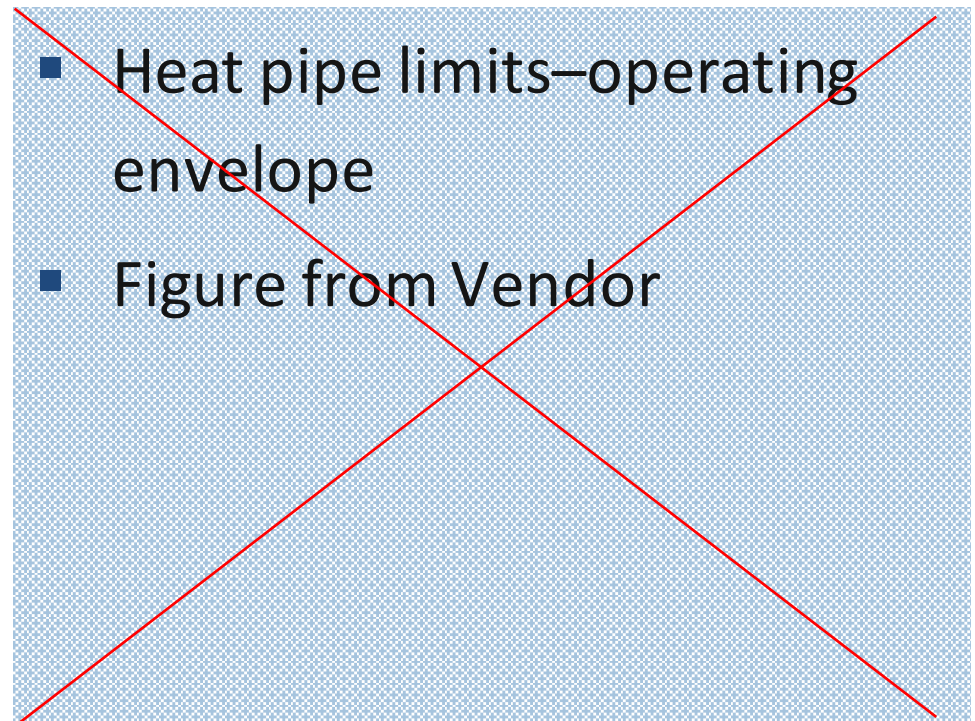
# Typical Characteristics of heat pipes

## Advantages:

- Very high effective thermal conductivity ( **$\sim 100 \text{ kW/m/K}$** ) compared to Cu ( **$0.4 \text{ kW/m/K}$** )
- **Vibration free** operation can be possible
- Can transport heat to a **large distance**
- They offer the possibility of **more compact design** and efficient means to remove heat
- Long Operating **Life (20+ years)** without any maintenance.
- Final heat removal can be done via conduction, or radiation heat transfer

# Heat pipe limits-operating envelope

- Transport Limitations
  - Viscous/ vapor pressure
  - Sonic
  - Entrainment
  - Boiling
  - Capillary Pressure



Reference: <http://www.thermopedia.com/content/835/>  
Example Heat Pipe Limitation Graph from Industry Vender [3]



# Vapor Pressure or Viscous Limit

- Usually occurs at start-up
- The minimum pressure at the condenser end of the pipe can be very small due to cold or hot start up and difference in temperature.
- The **vapor pressure drop between the extreme** end of the evaporator and the extreme end of the condenser, represents a restriction in operation.



# Sonic Limit

- At a temperature above the vapor pressure limit in the heat pipe, the **vapor** velocity can be comparable with **sonic velocity**
- At this point, the **vapor flow** within the heat pipe **becomes "choked"**.
- To avoid choked flow conditions (i.e., sonic limit) is to work below this limit of the maximum rate of heat transfer.

Reference: <http://www.thermopedia.com/content/835/>



# Entrainment Limit

- The **vapor velocity increases** with temperature and may produce very high **shear force** on the returning liquid flow from the condenser to the evaporator, which cause entrainment of the liquid towards evaporator by the flow of vapor.
- The restraining force on **liquid** counter by **surface tension**, **that** is a major parameter in determining the entrainment limit. Entrainment will cause a starvation of fluid. Restriction of fluid flow from the condenser and eventual "*dry out*" condition at the evaporator.

Reference: <http://www.thermopedia.com/content/835/>



# Circulation Limit

- The **driving pressure** for liquid circulation within the heat pipe is given by the capillary force established within the wick structure, given by following equation.

$$\Delta p_c \geq \Delta p_l + \Delta p_v + p_l g l \cos \phi$$

where  $\Delta p_l$  is the frictional pressure drop in liquid and  $\Delta p_v$  is the frictional pressure drop in the vapor.



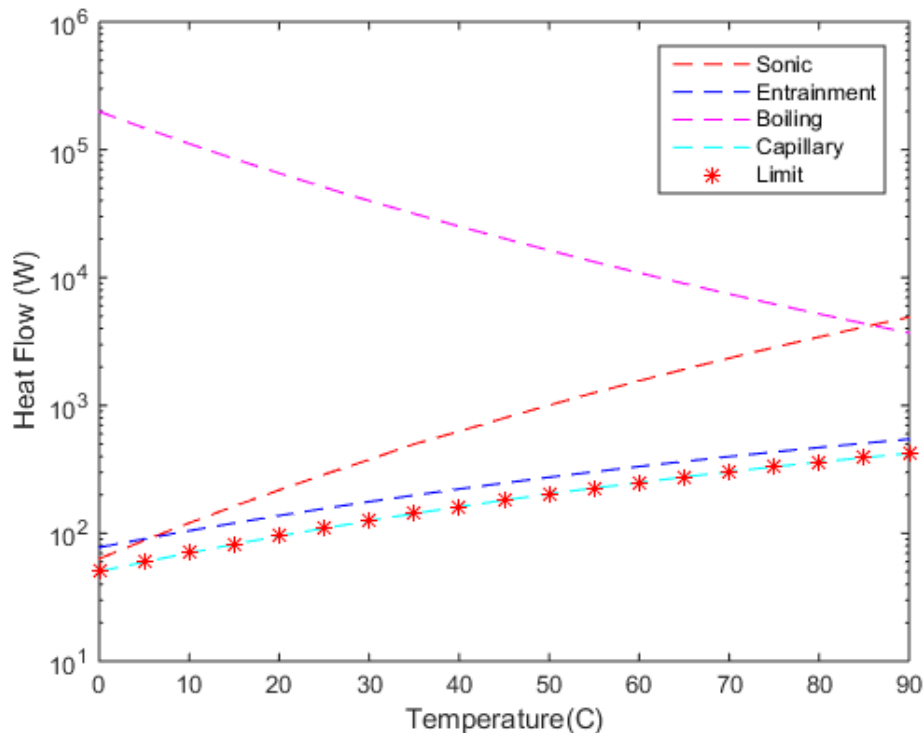
# Boiling Limit

- Excessive heat input can create this condition. The **temperature drop** across the wick structure in the evaporator region **increases** with increase in incoming heat flux.
- A point is reached when temperature difference exceeds the degree of superheat that can not sustain in relation to nucleate boiling conditions. This condition of the **onset of Boiling** within the wick structure can **interferes with liquid circulation**. This can lead to the "*dry out*" condition, while in the case of constant heat flux, this can cause "**Burn Out**" of the evaporator containment.



# Theoretical limits of Heat Pipe

*Heat Transfer Limitations on Feasible Heat Pipe Design*



*Heat Pipe Limitation Plot*

## ■ MATLAB

- 1000+ lines w/ GUI
- Outputs
  - Limitations Plot
  - Figure of Merit Plot
  - Maximum Heat Transport
  - Thermal Resistance
  - *Equivalent* Thermal Conductivity
  - Other characteristic values
- Optimization on Design Parameters



# Finite Element Analysis

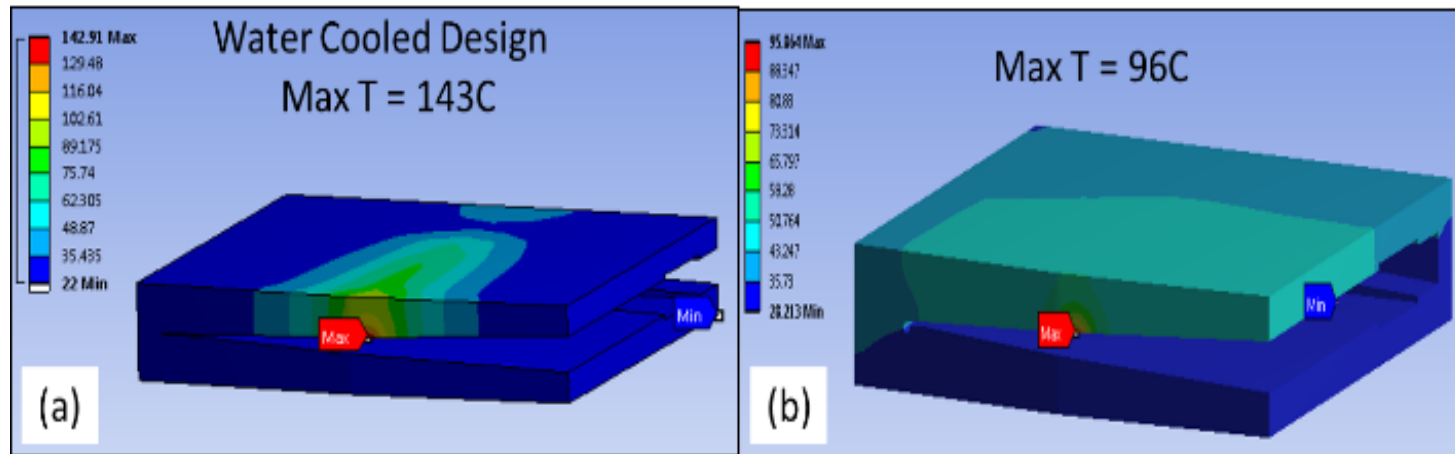


## FEA cases

1. Pipe is modelled as a **hyper conductive rod** by equivalent thermal conductivity
2. **Multiple layers** of the heat pipe are modelled
3. Variations on the **hyper-conductive rod and multiple layer** model simulations are performed which treat temperature as a constant 2-5°C difference and alter the conductivities to achieve this.
4. Treat the **heat pipe's temperature difference** as a few degrees constant. Set the contact thermal conductance to change the thermal conductivity of the heat pipe to achieve desired temperature change.



# FEA Comparison



- Generally, it was found that, regardless of the method used, a **heat pipe reduces the temperature** gradient on the absorber surface
- The **worst-cases scenarios** showed only a marginal improvement
- while others indicated a **larger benefit is achievable**, but all cases suggested that the heat pipe is a reasonable option in this application.

# FEA Results

- **Maximum Temperature often lower**, but when higher it still is within a reasonable range and only in the overestimate methods
- **Temperature gradient** improved even in worst of models



**Is it reliable?**



# RELIABILITY ISSUES

## *Start-up Conditions*

- During start up the **temperature gradient** may vary considerably.
- Conditions such as – **non uniform distributions** of the fluid, which lack condensable gases resulting in a **sudden drop off in temperature**.
- **Failure is a legitimate concern** under such conditions.



# *Structural Stability*

- It is important to note that heat pipes may be required to **withstand vibrations, shock, and severe temperatures.**
- Copper and GlidCop™, may be used to construct a heat pipe with very thin walls owing to the strengths of those materials.



## Reliability Issues continued....

- Possibilities include: **capillary pumping failure, boiling, dry-out from a frozen fluids restricting the self-replenishing nature, and entrainment of the liquid flow.**
- In addition, **low thermal resistance at the condenser** can overwhelm the system and enhance the probability that such failures will occur.
- There are **ways to avoid some of these failure modes**, for example utilizing an entrainment limit which exceeds sonic limit.
- However, solutions to such problems, and the degree to which they may be avoided are strongly dependent on the **specific application.**





# Manufacturing Concerns

- The development of a **shell**, the insertion of a **wick**, and filling the pipe with fluid as it is sealed off at one of the ends.
- Afterwards, some **experimentation** is needed on any given heat pipe to **ensure it performs as intended**.
- At the same time, to achieve the design needed, **the evaporative section needs to be built into the absorber** itself for all the heat pipes.
- The precise of manufacturing methods can also generate **heat pipe with different pressure** in each product and it does offer **concerns that arise from manufacturing process**.



## *Contact Variance*

- Another major concern is the thermal interaction between the heat pipe and the absorber.



# *Material Compatibility for Operation*

- Some fluid and solid combinations will result in chemical reactions that develop gas pockets which hamper or cease operation of the heat pipe.
- Water is known to be generally compatible with copper however compatibility between water and GlidCop™- another common absorber material, is less established.
- The Acetone or some refrigerants would be some potential alternatives by being compatible with both.
- However, these would offer notable downgrades in performance capabilities.



**Solution?**



# Other Two-Phase Heat Exchanger Solutions

- Flat Heat Pipe (“Vapor Chamber”)

- Geometric Challenge
- Spreads Effectively

- Vapor Chamber image

*Vapor Chamber [5]*

- Pumped Two Phase Cooling

- Typically Isothermal
- High Heat Flux Capacity
- Requires Lower Flowrate

- Vapor Two phase cooling system image

*Pumped Two Phase Cooling Diagram [6]*



# Conclusion

- **Heat pipes offer an attractive solution** for efficient and compact transport of heat in photon absorber applications.
- **Simulations** show that heat pipes offer **tangible improvements** over conventional water cooling.
- However, a number of **potential limitations** should be weighed against the performance improvements.
- These include potentially more complex and **costly fabrication, limited operational predictability, and reliability.**
- **Continued investigation is warranted**, particularly as the requirements for next generation accelerators continue to become more challenging.



# Acknowledgements

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# Questions?

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